Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Aug 09, 2014 02:39 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
FDMS7656AS	FDMS7656AS	8-PQFN 5X6 (TFSnCuAlBW)			INTERNAL CEBU	**0.105956**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	**Declaration Type * Custom**

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	**4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name 8-PQFN 5X6 (TFSnCuAlBW)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	5.090	Supplier		Silicon	5.090	7440-21-3	48039
Die Attach	Other Nonferrous metals & alloys	6.941	A	Lead/Lead Compounds	Lead	6.420	7439-92-1	60591
			Supplier		Silver	0.174	7440-22-4	1642
			Supplier		Tin	0.347	7440-31-5	3275
Encapsulation	Thermoplastics	44.400	Supplier		Carbon Black	0.444	1333-86-4	4190
			Supplier		Epoxy Resin	2.220	29690-82-2	20952
			Supplier		Metal Hydroxide - Generic CAS#	2.220	G0007	20952
			Supplier		Phenolic resin	1.332	9003-35-4	12571
			Supplier		Silica, vitreous	38.184	60676-86-0	360375
Lead Frame	Copper & its alloys	35.434	Supplier		Copper	34.500	7440-50-8	325606
			Supplier		Iron	0.850	7439-89-6	8022
			Supplier		Silver	0.038	7440-22-4	361
			Supplier		Zinc	0.046	7440-66-6	434
Terminal Finish	Other Nonferrous metals & alloys	13.500	Supplier		Tin	13.500	7440-31-5	127411
Wire Bond	Copper & its alloys	0.591	Supplier		Aluminum	0.584	7429-90-5	5511
			Supplier		Copper	0.007	7440-50-8	67